

FK1105: AgPt via filling paste

The AgPt via filling FK1105 exhibits very little sinter shrinkage, in order to fill the via as completely as possible. This helps to establish contact between buried and surface metallization of multi-layer ceramics.

Processing

Substrates

The paste is designed for use on AlN substrates (with lapped surfaces) from CoorsTek/ANCeram. Substrates with other surface qualities or from other manufacturers may lead to variations in the results.

Stencil printing

The paste can be used for the metallization of vias in aluminum nitride and alumina. To fill the vias as fully as possible, stainless steel stencils should be used which are adapted to fit the thickness of the substrates. With regard to the via openings in the stencils, Fraunhofer IKTS recommends making the openings approx. one to five percent wider than the via diameters introduced in the ceramics.

Levelling

The screen printed film should level for 10±2 minutes at room temperature (22 to 25 °C).

Drying

After leveling, the films are dried at 150 °C for 15 minutes in a well ventilated drying furnace. A conveyor dryer can also be used.

Firing

The films should be fired in air at a peak temperature of 850 °C, a dwell time of 10 minutes and a total cycle time of 30 minutes in a belt furnace. In order to achieve gas-tight fillings, a special infiltration glass paste of the FK4800 series needs to be applied in a subsequent step.

Storage

The paste should be stored at 4 to 10 °C. This guarantees a high paste viscosity and prevents the solids from settling. The jar must remain tightly closed during storage. To prevent condensation of air humidity on the paste, the jar must not be opened until the contents have reached room temperature. Before using the paste, it must be sufficiently homogenized, for example by stirring it with a spatula.

Safety notice

For safe handling and storage, also observe the advice of current material safety data sheets.

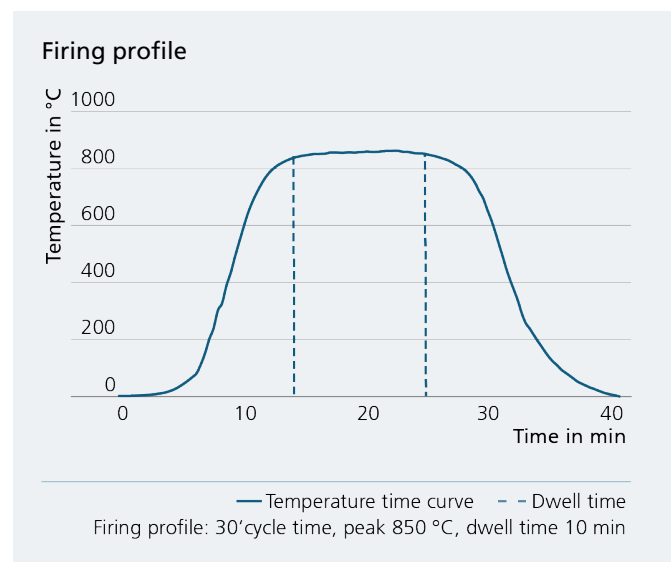
Quality requirements

Each delivery will be supplied with Certificate of Analysis (CoA). The paste meets all requirements of RoHS III (regulation 2015/863/EC) and REACH (regulation (EC) 1907/2006).

Instead of an expiration date, after which an expired paste would have to be disposed of regardless of its condition, it is provided with a retest date. The certified values of the paste are valid for six months from the date of shipment of the unopened jars. Prolonged storage may result in segregation of the solids. Then the paste should be mixed thoroughly before further use. After the retest date the customer can decide whether the product needs to be retested to recheck the parameters for further application. The test conditions are given in point 2 to compare the results with CoA.

Miscellaneous

The current technical specifications are published on our website www.ikts.fraunhofer.de.



Technical specifications

Parameter	Unit	Value
Viscosity ¹	Pa·s	TBD
Sheet resistance ^{2, 6}	mOhm/sq	≤ 10
Solderability ^{3, 6}	%	TBD
Leaching resistance ^{4, 6}	Dips/result	TBD
Adhesion ⁵ (number of firings)		
- Initial ⁶ (1 x fired)	N/4 mm ²	TBD
- Aged ⁶ (1 x fired)		TBD
Fired film thickness	µm	15±1
Coverage ⁷	cm ² /g	63±5

¹ Brookfield viscometer HB with spindle/cup combination SC4-14/-6RP(Y) at n=10 rpm and 25±0.2 °C.

² Sheet resistance, calculated for a fired thickness of 15±1 µm.

³ Solder Sn/Pb/Ag 63/35.5/1.5; flux: Alpha 611, soldering time: 5 s, soldering temperature: 220±2 °C.

⁴ Solder Sn/Pb/Ag 63/35.5/1.5; flux: Alpha 611, soldering time: 5 s, soldering temperature: 230±2 °C.

⁵ 90° wire peel test in accordance with DIN 41850-2, 2x2 mm² pad size, solder: Sn/Pb/Ag 63/35.5/1.5, artificial aging time 100 h at 150 °C.

⁶ Firing profile: total cycle time 30 min, 10 min at 850 °C.

⁷ Calculated area that can be printed with one gram paste in the recommended thickness.

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REACH
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